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IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
JUNICHI ASADA : EXAMINER: CHU, C.
SERIAL NO: 09/740,902 :
FILED: DECEMBER 21, 2000 : GROUP ART UNIT: 2815
FOR: SEMICONDUCTOR DEVICE :

RECEIVED
JAN 30 2002
TECHNOLOGY CENTER 2800

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated October 26, 2001, please amend this application as follows:

IN THE SPECIFICATION

Please amend the specification as shown below and in the marked-up copy following this amendment.

✓ Please replace the paragraph bridging pages 16 and 17 as follows:

On the other hand, a polyimide film 42 having a thickness of 75 μm is used as the interposer for supporting the chip 41 and holding a lead wire 43. The polyimide film 42 has an opening portion 46 called a device hole. One end portion of the lead wire 43, which is formed of, for example, a copper foil, extends into the opening portion 46 so as to be connected directly to a connection electrode (pad) 44 formed on the surface of the chip 41 by